

Series: Ceramic Chip Antenna

TECHNICAL DATA SHEET

Description: Quad Band Monopole Ceramic

Chip Antenna

PART NUMBER: W3073



Features:

Frequency:

824-894/1710-2170MHz or 880-960/1710-2170MHz

- Size 10 x 3.2 x 4 mm
- PCB Keep out 40 x 10 mm
- Polarization Linear
- Radiation pattern Omni

Applications:

- 2G/3G
- Nb-loT
- GSM850 or EGSM900/, PCN1800, PCS1900 and **WCDMA**

All dimensions are in mm / inches

Issue: 2037

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ELECTRICAL SPECIFICATIONS

Antenna Type Chip antenna

Frequency Version1: 868-870MHz

1710-2170MHz

Version2: 880-960MHz

1710-2170MHz

 $\begin{array}{lll} \mbox{Nominal Impedance} & & 50 \ \Omega \\ \mbox{Radiation Pattern} & & \mbox{Omni} \\ \mbox{Polarization} & & \mbox{Vertical} \\ \mbox{Power Withstanding} & & 3W \\ \end{array}$

MECHANICAL SPECIFICATIONS

Compact size 10 x 3.2 x 4mm
Weight 0.6g
Fixing system SMT

MSL(MOISTURE SENSITIVITY LEVEL)

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature $-40 \sim +85^{\circ}$ C Storage Temperature $-10 \sim +30^{\circ}$ C RoHS Compliant Yes





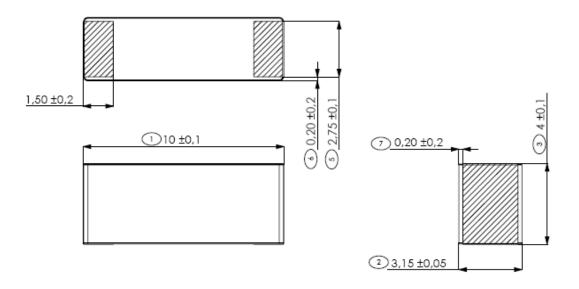
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MECHANICAL DRAWING



No.	Terminal Name	Terminal Dimensions		
1	Feed	1.5 x 2.75 mm		
2	Support pad	1.5 x 2.75 mm		
Antenna is symmetrical and orientation on footprint can be rotated				
180 degrees without change in performance				





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PWB Layout

Test Setup for Electrical Measurements

Recommended test board- layout for electrical characteristic measurement. Test board outline size 105 x 40mm. Ground cleared under antenna 40mm x 10mm.

Version 1: GSM850, PCN1800, PCS1900 and WCDMA I Layout in Top Copper All metallization Gr should be removed from all PWB layers on ground clearance area (10.00 x 40.00 mm) Ground Clearance Area (10.00mm x 40.00mm) 40 0,45 W3073 Ceramic chip antenna location GSM850 frequency tuning area 1,60 PWB layout depends on aplication and 1,85 surrounding mechanics / materials. 3,75 10,60 20,60 Ground Area Component Layout in Bottom Copper size 0805 (2 pcs) Ground Via Hole Ground area should be surrounded with Ground Via Holes Foed line 50 Ohm Any type of 50 Ohm feed line can be used. Inner layers on feed line area need to designed to give 50 Ohm characteristics to feed line. 0 0 0 0 Component size 0603 Feed conta 0,15 2pcs of Cu Via holes to top side of PWB 0,30 D 0,45 Stub for PCN1800, PCS1900 and WCDMA I 0,80 frequency tuning 3,35 Length depends on application and surrounding mechanics / materials.

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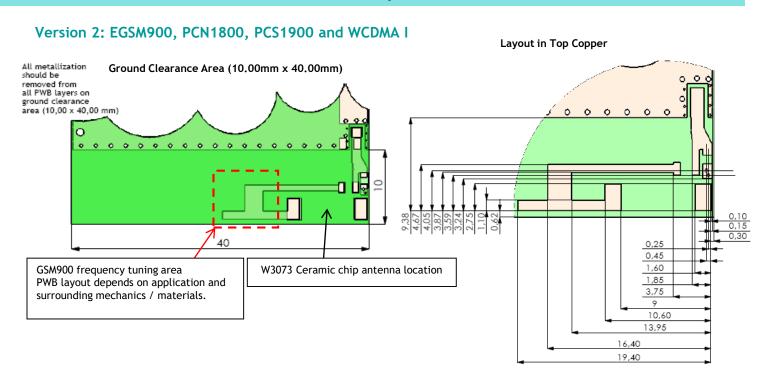
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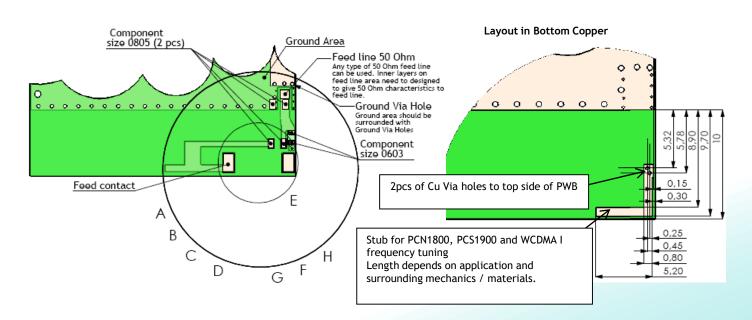
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PWB Layout





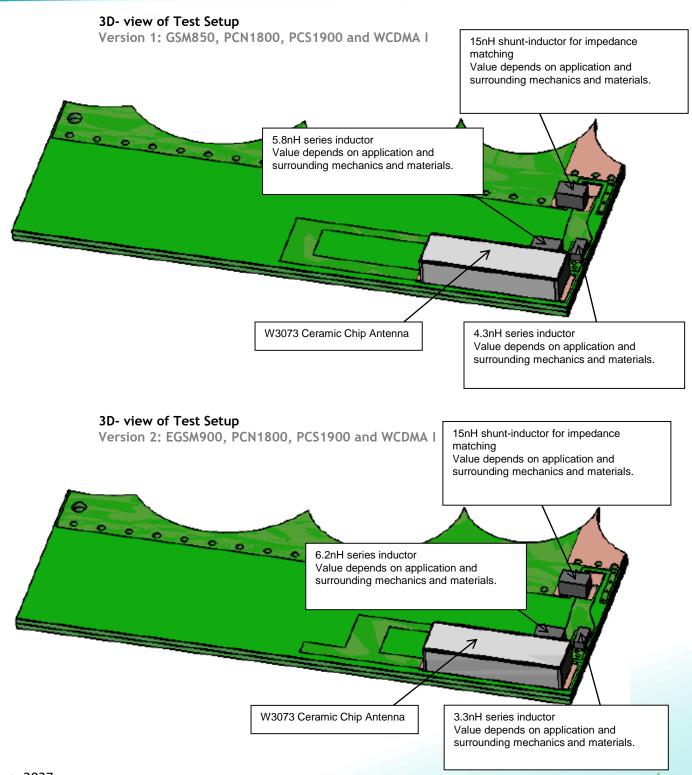


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ROHS



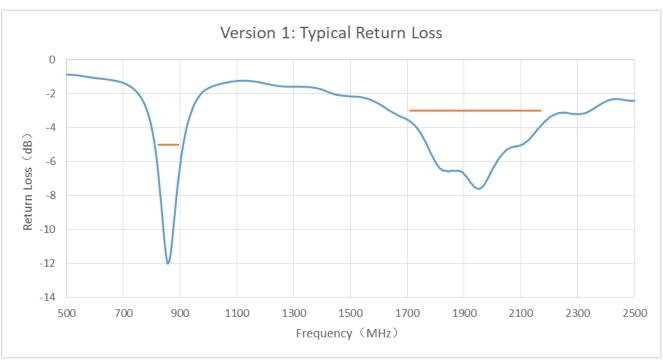
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GHARTS







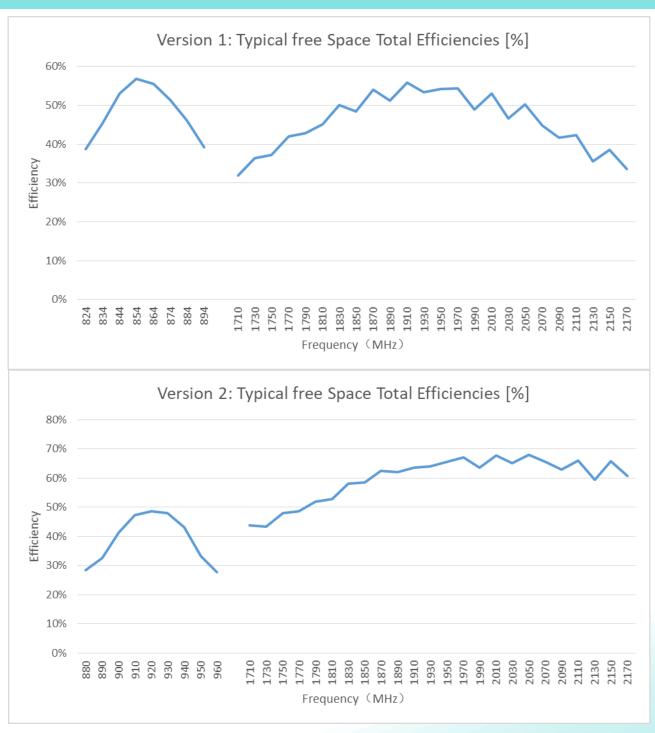
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CHARTS







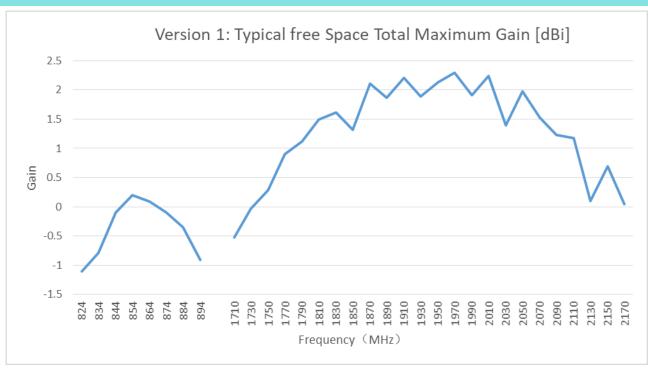
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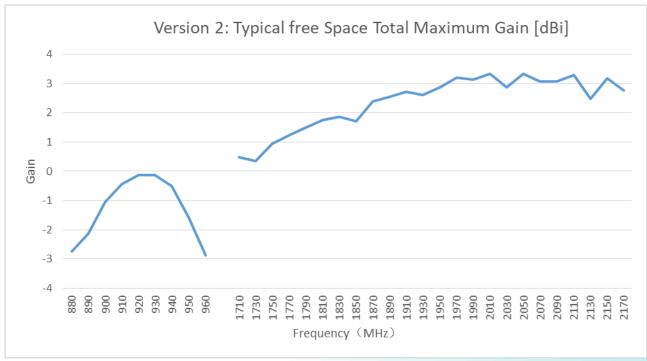
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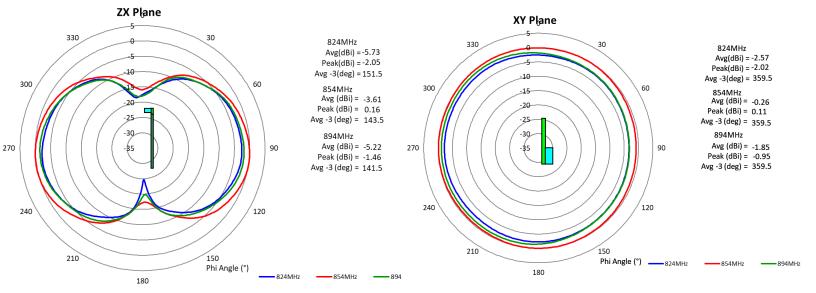
Chip Antenna

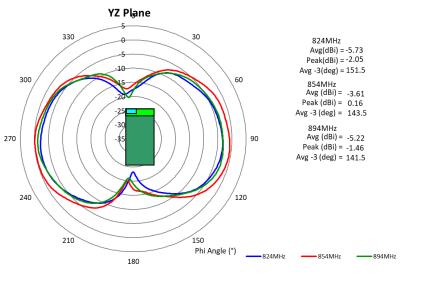
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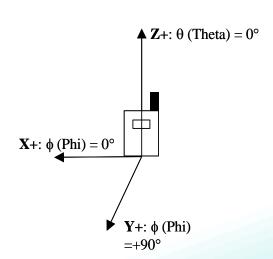
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CHARTS

Version 1: Typical Free Space Radiation Patterns









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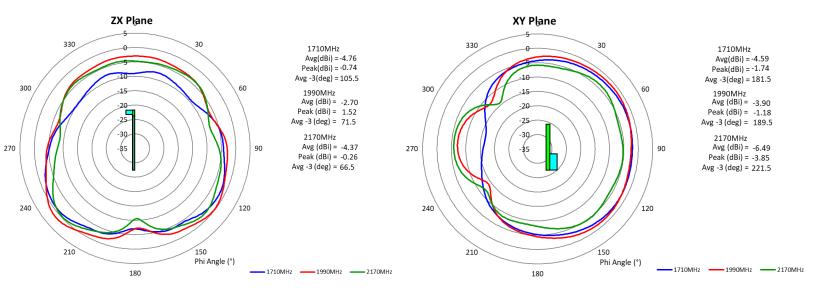
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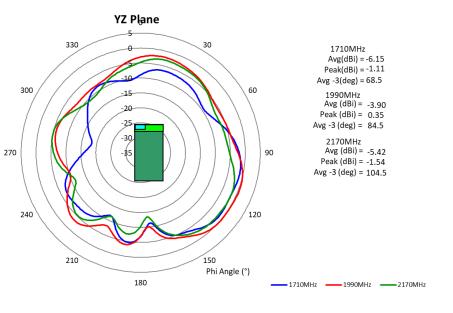
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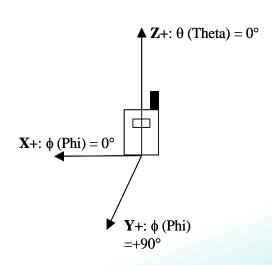
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CHARTS

Version 1: Typical Free Space Radiation Patterns









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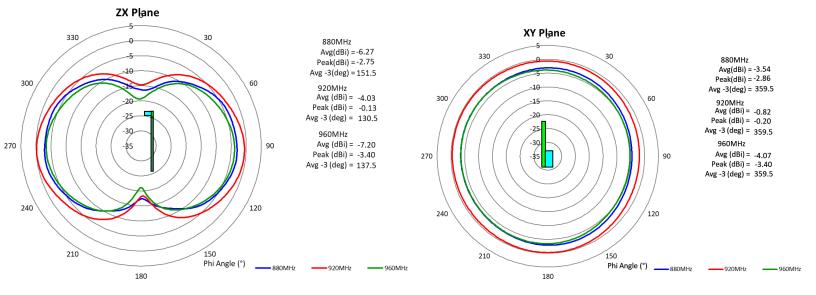
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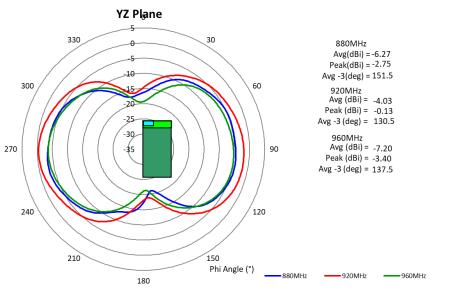
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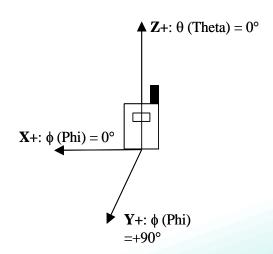
Series: Ceramic Chip Antenna

CHARTS

Version 2: Typical Free Space Radiation Patterns









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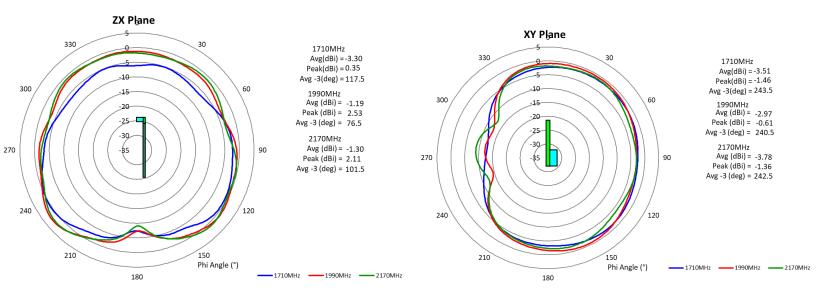
Chip Antenna

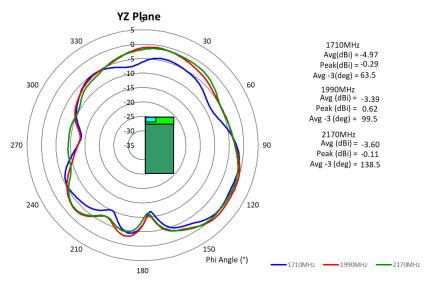
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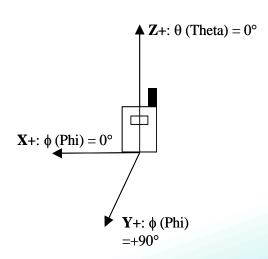
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CHARTS

Version 2: Typical Free Space Radiation Patterns









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Recommendations for ceramic chip antenna storage

Storage time

Products should be used within 6 months from the day of manufacturers packaging even when they are stored under below mentioned conditions. Longer storage period may decrease the component solderability.

Storage environmental conditions

To maintain solderability of Pulse ceramic products care must be taken to control the storage and use conditions:

- Do not store or use products in a corrosive atmosphere, especially where chloride, sulphur or sulfide, alkali or acid salts exist in the air. Corrosive gases may cause oxidation of electrodes and reduce solderability
- Keep temperature and humidity stabile and do not exceed the below mentioned minimum and maximum conditions: Temperature: -10 to +30 Deg C Humidity: below 60% RH
- Do not store the products under direct sun light.

It is recommended to keep the products in manufacturers packing (tape&reel) until the time of assembly and soldering process. Air tight vacuum package is recommended in the conditions where it is know to be some corrosive gases.

Handling

Do not touch the components with bare hands. Protective gloves must be used to prevent contamination of terminals which may cause reduced solderability. Do not touch or damage the silver plated surface by any sharp objects. Soft materials (plastic, wood etc.) must be used if tweezers or other tools are used to pick the components. Avoid any excess mechanical shock or vibration during storage and handling.





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Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s

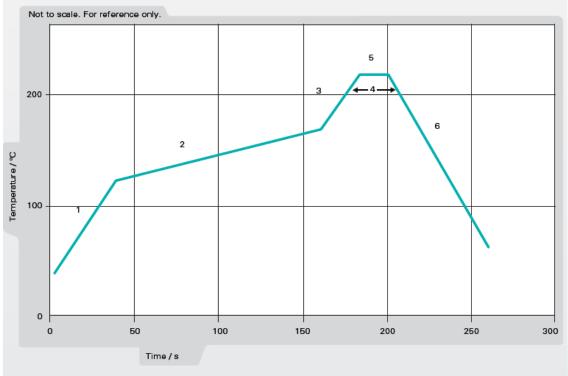


Figure 1. Minimum temperature profile recommendation for reflow soldering process



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1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

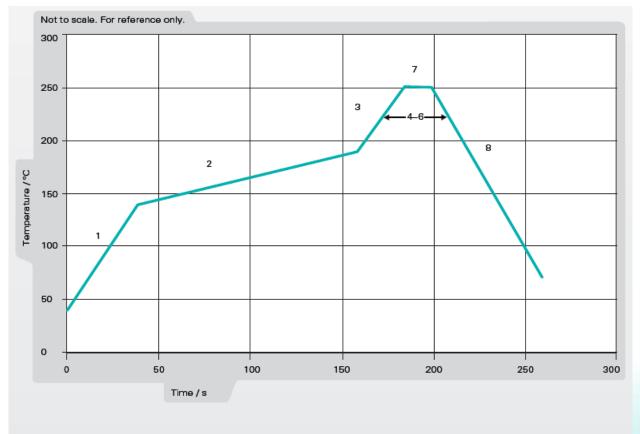


Figure 2. Maximum temperature profile recommendation for reflow soldering process



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PACKAGING

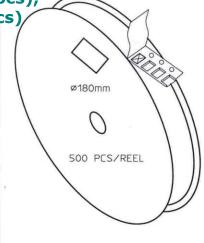
Packing form

Issue: 2037

500pcs in one Reel,

3 reel in one inbox (1500 pcs),

2 inbox in out box (3000pcs)



CARRIER TAPE H85-00158 width=24,00 depth=4.15 COVER TAPE H85-00159 width=21.20

LENGTH OF TAPE:

- Leader section: min 350 mm before component section
- Trailer section: min 40 mm after component section.

Empty part cavities at leader and trailer section of the tape must be sealed with top cover tape.

BOX H85-00128 (182x182x125)

1 pcs

- LABEL

1 pcs/BOX

REEL H85-00160 (D180, W28)

4 pcs

- REEL LABEL

1 pcs/REEL

MATERIAL HANDLINGS RATIO DRWN 160107 PeHa H DGNER G CHKD APPRD PRODUCT APPRD BY D H90-0Y800-F01P01 В

DENOMINATION PACKING FORM

VERSION MOD/DATE/NAME RóHS



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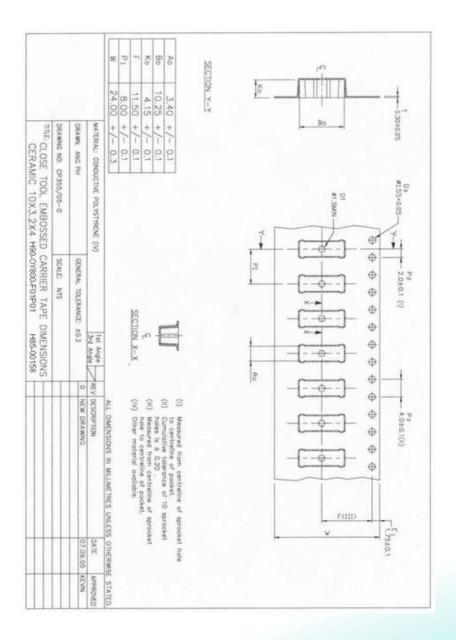
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PACKAGING

General

Tape and reel packing is used. Carrier tape, reel and box dimensions are presented in following pictures.

Carrier tape



单击下面可查看定价,库存,交付和生命周期等信息

>>Pulse(普思)